



Metal Film Low-Resistance Chip Resistor

KDV Series Material Declaration Statement					KDV02		KDV04		KDV06		KDV08		KDV12	
No	Breakdown of Part	Substance Name	CAS No.	%	Total(mg)	0.182037	Total(mg)	0.575500	Total(mg)	2.090909	Total(mg)	4.846435	Total(mg)	8.551079
					Weight (mg)	Percentage (%)	Weight (mg)	Percentage (%)	Weight (mg)	Percentage (%)	Weight (mg)	Percentage (%)		
1	Ceramic Substrate	Al2O3	1344-28-1	96.0	0.14268	78.38%	0.512136843	88.99%	1.854717	88.70%	4.327660	89.30%	7.89500	92.33%
		SiO2	14808-60-7	2.9										
		CaO	1305-78-8	0.6										
		MgO	1309-48-4	0.5										
2	Innerelectrode (C1)	Cu	7440-50-8	100	0.01387	7.62%	0.015384201	2.67%	0.055714	2.66%	0.087597	1.81%	0.10526	1.23%
3	Innerelectrode (C2)	Cu	7440-50-8	55	0.00335	1.84%	0.005209937	0.91%	0.018868	0.90%	0.036909	0.76%	0.02632	0.31%
		Ni	7440-02-0	44										
		Mn	7439-96-5	1										
4	Resistive Layer	Cu	7440-50-8	55	0.01029	5.65%	0.018391079	3.20%	0.066604	3.19%	0.130288	2.69%	0.13158	1.54%
		Ni	7440-02-0	44										
		Mn	7439-96-5	1										
5	Termination-Side	Ni	7440-02-0	80	0.0001	0.05%	0.000155212	0.03%	0.000562	0.03%	0.001052	0.02%	0.00125	0.01%
		Cr	7440-47-3	20										
6	Termination(Ni)	Ni	7440-02-0	100	0.001369	0.75%	0.000927893	0.16%	0.003360	0.16%	0.007057	0.15%	0.01038	0.12%
7	Termination(Sn)	Sn	7440-31-5	100	0.001148	0.63%	0.000828164	0.14%	0.002999	0.14%	0.006298	0.13%	0.00974	0.11%
8	Bottom Protective Overcoat-1	Epoxy Resin	25068-38-6	100	0.00424	2.33%	0.01359117	2.36%	0.049221	2.35%	0.147572	3.04%	0.17544	2.05%
9	Bottom Protective Overcoat-2	Epoxy Resin	25068-38-6	100	0.00237	1.30%	0.004392924	0.76%	0.015909	0.76%	0.035044	0.72%	0.08772	1.03%
10	Top Protective Overcoat	Epoxy Resin	25068-38-6	100	0.00262	1.44%	0.004482576	0.78%	0.016234	0.78%	0.043179	0.89%	0.10526	1.23%
11	Marking	Epoxy Resin	25068-38-6	100	None	None	None	None	0.006721	0.32%	0.023780	0.49%	0.00313	0.04%